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Stocking Distributor

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[Texas Instruments](#)
[LM293MDREP](#)

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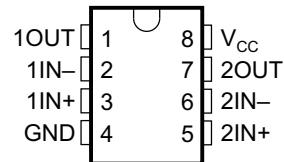
FEATURES

- Controlled Baseline
 - One Assembly
 - Test Site
 - One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product Change Notification
- Qualification Pedigree ⁽¹⁾
- Single Supply or Dual Supplies
- Wide Range of Supply Voltage
 - Max Rating . . . 2 V to 36 V
 - Tested to 30 V

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold-compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Low Supply-Current Drain Independent of Supply Voltage . . . 0.4 mA Typical Per Comparator
- Low Input Bias Current . . . 25 nA Typical
- Low Input Offset Voltage . . . 2 mV Typical
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ± 36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS

LM293 . . . D PACKAGE
 (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This device consist of two independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM293-EP is characterized for operation from -55°C to 125°C .

ORDERING INFORMATION⁽¹⁾

T _A	V _{IOMAX} AT 25°C	MAX V _{CC}	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOPSIDE MARKING
-55°C to 125°C	5 mV	30 V	SOIC – D	Reel of 2500	LM293MDREP	LM293E

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
 (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

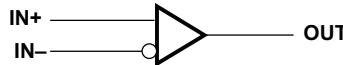


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

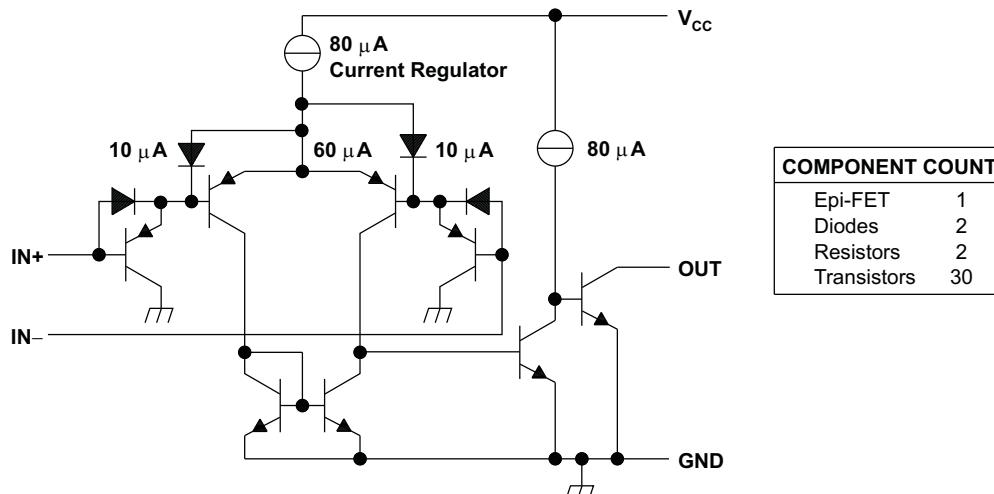
LM293-EP
DUAL DIFFERENTIAL COMPARATOR

SLCS155—OCTOBER 2007

Symbol (Each Comparator)



Schematic (Each Comparator)



Current values shown are nominal.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾		36	V
V _{ID}	Differential input voltage ⁽³⁾		±36	V
V _I	Input voltage range (either input)	-0.3	36	V
V _O	Output voltage		36	V
I _O	Output current		20	mA
	Duration of output short-circuit to ground ⁽⁴⁾		Unlimited	
θ _{JA}	Package thermal impedance ⁽⁵⁾⁽⁶⁾	D package	97	°C/W
T _J	Operating virtual junction temperature		150	°C
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to GND.
- (3) Differential voltages are at IN+, with respect to IN-.
- (4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
- (5) Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) - T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

Electrical Characteristics

at specified free-air temperature, $V_{CC} = 5$ V (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$T_A^{(1)}$	LM293			UNIT
			MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{CC} = 5$ V to 30 V, $V_O = 1.4$ V, $V_{IC} = V_{IC(min)}$	25°C		2	5	mV
		Full range			9	
I_{IO} Input offset current	$V_O = 1.4$ V	25°C		5	50	nA
		Full range			250	
I_{IB} Input bias current	$V_O = 1.4$ V	25°C		-25	-250	nA
		Full range			-400	
V_{ICR} Common-mode input voltage range ⁽²⁾		25°C	0 to $V_{CC} - 1.5$			V
		Full range	0 to $V_{CC} - 2$			
A_{VD} Large-signal differential-voltage amplification	$V_{CC} = 15$ V, $V_O = 1.4$ V to 11.4 V, $R_L \geq 15$ k Ω to V_{CC}	25°C	50	200		V/mV
I_{OH} High-level output current	$V_{OH} = 5$ V, $V_{ID} = 1$ V	25°C		0.1	50	nA
	$V_{OH} = 30$ V, $V_{ID} = 1$ V	Full range			1	μ A
V_{OL} Low-level output voltage	$I_{OL} = 4$ mA, $V_{ID} = -1$ V	25°C	150	400		mV
		Full range			700	
I_{OL} Low-level output current	$V_{OL} = 1.5$ V, $V_{ID} = -1$ V	25°C	6			mA
I_{CC} Supply current	$R_L = \infty$	$V_{CC} = 5$ V	25°C	0.8	1	mA
		$V_{CC} = 30$ V	Full range		2.5	

- (1) Full range (MIN or MAX) for LM293 is -55°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (2) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is $V_{CC+} - 1.5$ V for the inverting input (-), and the non-inverting input (+) can exceed the V_{CC} level; the comparator provides a proper output state. Either or both inputs can go to 30 V without damage.

Switching Characteristics

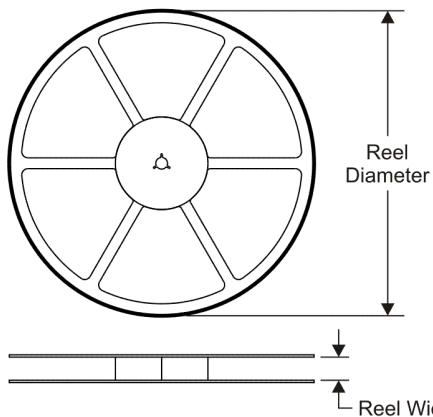
$V_{CC} = 5$ V, $T_A = 25$ °C

PARAMETER	TEST CONDITIONS	LM293		UNIT
		TYP	UNIT	
Response time	R_L connected to 5 V through 5.2 k Ω , $C_L = 15$ pF ⁽¹⁾ , See ⁽²⁾	100 mV input step with 5 mV overdrive	1.3	μ s
		TTL-level input step	0.3	

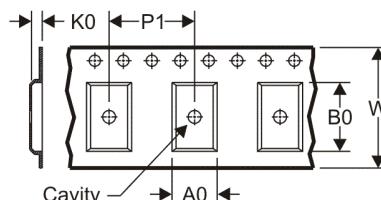
- (1) C_L includes probe and jig capacitance.
- (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

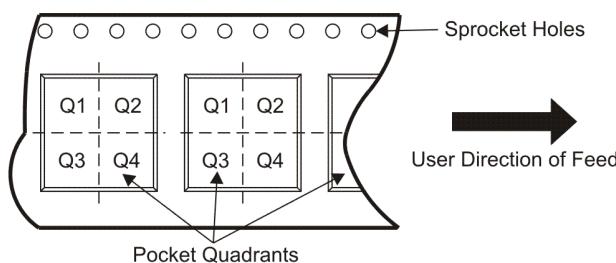


TAPE DIMENSIONS



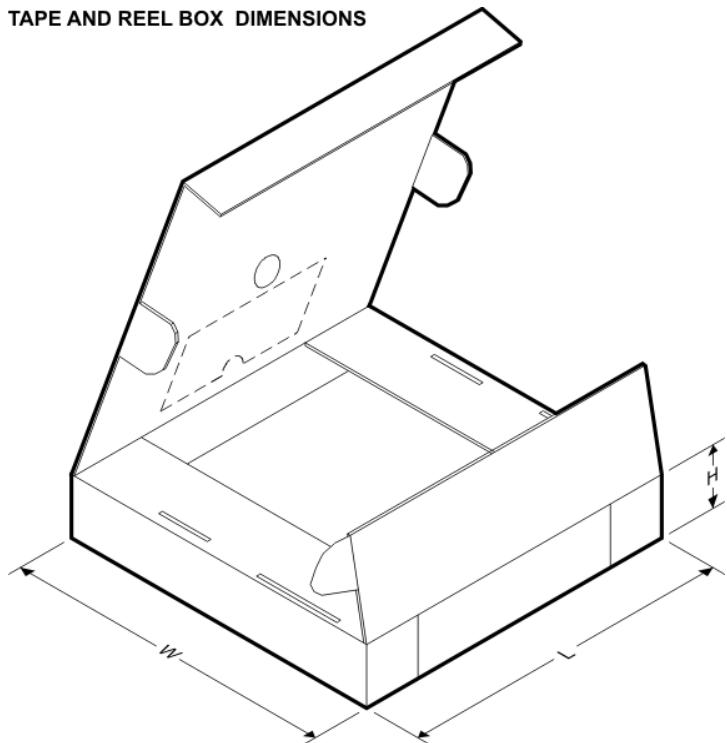
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM293MDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

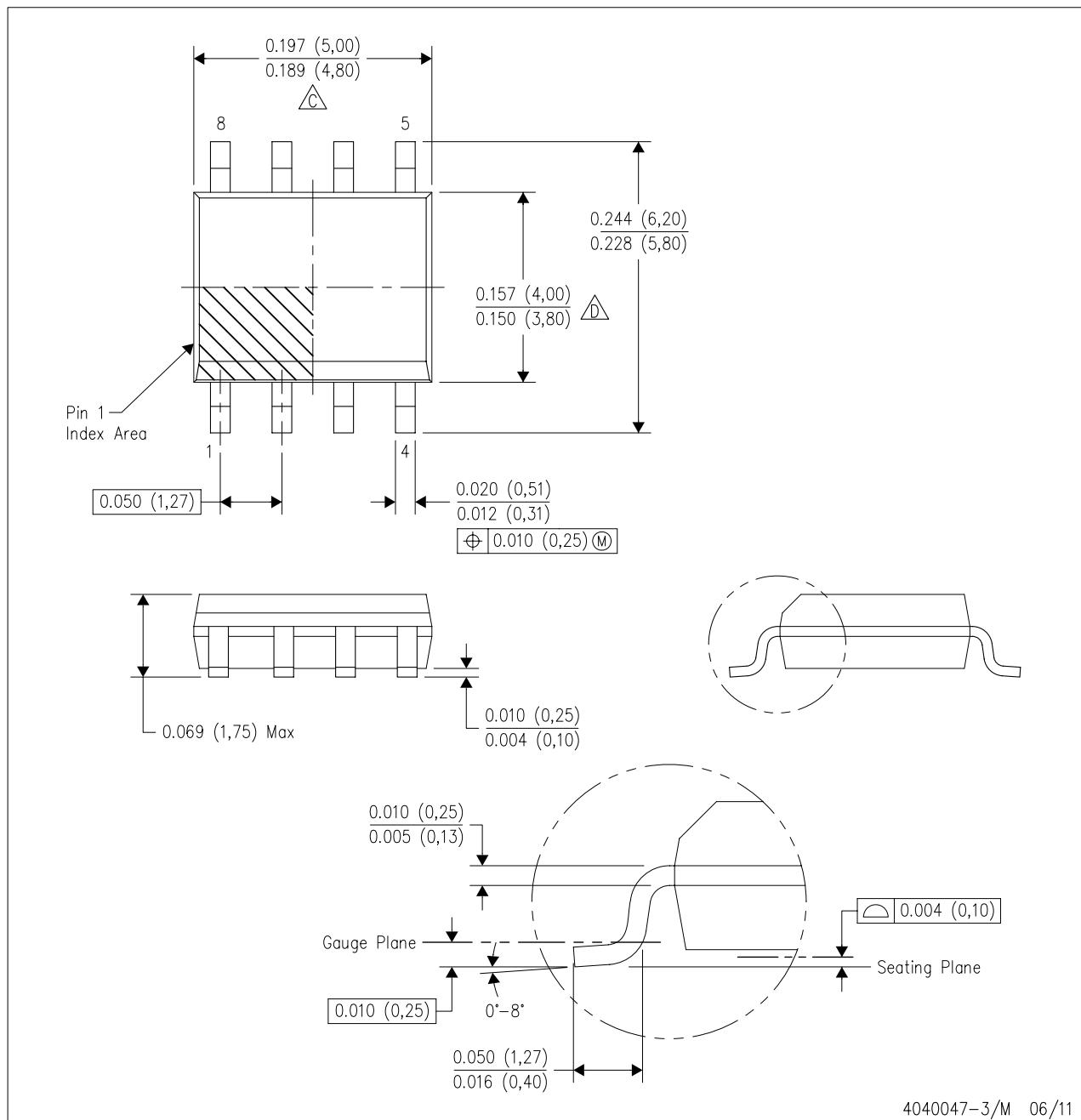
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM293MDREP	SOIC	D	8	2500	340.5	338.1	20.6

MECHANICAL DATA

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

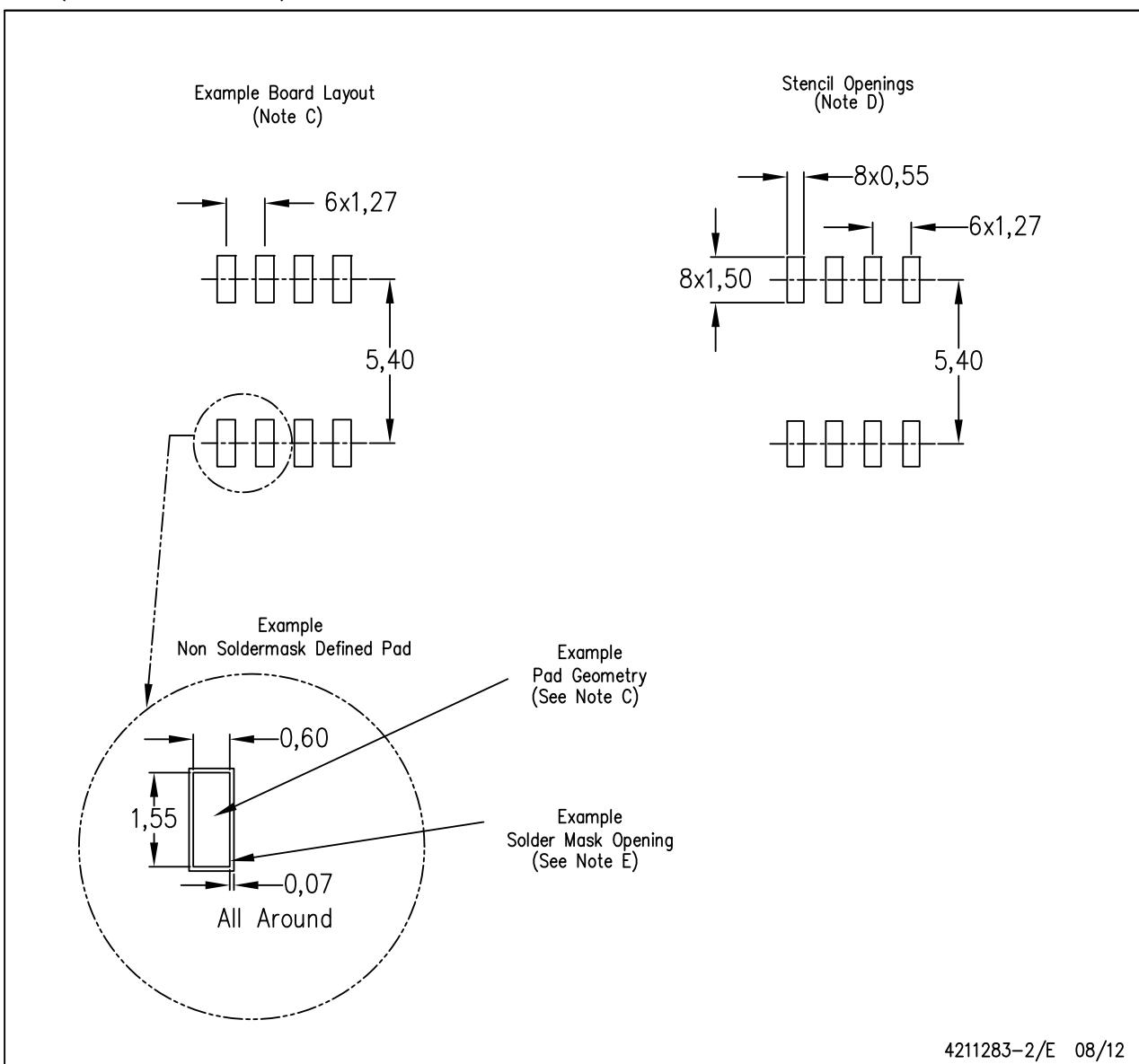
Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AA.

LAND PATTERN DATA

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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